

Session Title: [TE1] Equipment, Process, Metrology

Session Date: November 15 (Tue.), 2022

Session Time: 09:30-10:50

Session Room: Room E (Grand Ballroom 3, 2F)

Session Chair: Prof. Hak Sung Kim (Hanyang Univ., Korea)

[TE1-1] 09:30-09:50

EBSD Measurement and Calculation for Microstructure Formation of Metal Electrodeposits by Organic Additives

Hyo-Jong Lee, Han-Kyun Shin, Sang-Hyeok Kim, and Hyun Park (Dong-A Univ., Korea)

[TE1-2] 09:50-10:10

Trends of Low-Temperature Bonding Technologies Using Gallium and Gallium Alloys Yoonchul Sohn (Chosun Univ., Korea)

[TE1-3] 10:10-10:30

Mechanical Evaluation of Heterogeneous Interfaces in Electronic Package

Jae Yong Song (POSTECH, Korea)

[TE1-4] 10:30-10:50

Novel Electrodeposition for Advanced Semiconductor Package

Jinhyun Lee, Haneul Han, Sanhwa Yoon, and Bongyoung Yoo (Hanyang Univ., Korea)